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# Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

## **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	262400
Number of Logic Elements/Cells	695000
Total RAM Bits	51200000
Number of I/O	840
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1932-BBGA, FCBGA
Supplier Device Package	1932-FBGA, FC (45x45)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgsed8n2f45i3n

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Electrical Characteristics Page 3

Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 2 of 2)

Symbol	Description	Minimum	Maximum	Unit
V <sub>CCD_FPLL</sub>	PLL digital power supply	-0.5	1.8	V
V <sub>CCA_FPLL</sub>	PLL analog power supply	-0.5	3.4	V
V <sub>I</sub>	DC input voltage	-0.5	3.8	V
T <sub>J</sub>	Operating junction temperature	-55	125	°C
T <sub>STG</sub>	Storage temperature (No bias)	-65	150	°C
I <sub>OUT</sub>	DC output current per pin	-25	40	mA

Table 4 lists the absolute conditions for the transceiver power supply for Stratix V GX, GS, and GT devices.

Table 4. Transceiver Power Supply Absolute Conditions for Stratix V GX, GS, and GT Devices

Symbol	Description	Devices	Minimum	Maximum	Unit
V <sub>CCA_GXBL</sub>	Transceiver channel PLL power supply (left side)	GX, GS, GT	-0.5	3.75	V
V <sub>CCA_GXBR</sub>	Transceiver channel PLL power supply (right side)	GX, GS	-0.5	3.75	V
V <sub>CCA_GTBR</sub>	Transceiver channel PLL power supply (right side)	GT	-0.5	3.75	V
V <sub>CCHIP_L</sub>	Transceiver hard IP power supply (left side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCHIP_R</sub>	Transceiver hard IP power supply (right side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCHSSI_L</sub>	Transceiver PCS power supply (left side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCHSSI_R</sub>	Transceiver PCS power supply (right side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCR_GXBL</sub>	Receiver analog power supply (left side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCR_GXBR</sub>	Receiver analog power supply (right side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCR_GTBR</sub>	Receiver analog power supply for GT channels (right side)	GT	-0.5	1.35	V
V <sub>CCT_GXBL</sub>	Transmitter analog power supply (left side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCT_GXBR</sub>	Transmitter analog power supply (right side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCT_GTBR</sub>	Transmitter analog power supply for GT channels (right side)	GT	-0.5	1.35	V
V <sub>CCL_GTBR</sub>	Transmitter clock network power supply (right side)	GT	-0.5	1.35	V
V <sub>CCH_GXBL</sub>	Transmitter output buffer power supply (left side)	GX, GS, GT	-0.5	1.8	V
V <sub>CCH_GXBR</sub>	Transmitter output buffer power supply (right side)	GX, GS, GT	-0.5	1.8	V

## **Maximum Allowed Overshoot and Undershoot Voltage**

During transitions, input signals may overshoot to the voltage shown in Table 5 and undershoot to -2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

Electrical Characteristics Page 5

## **Recommended Operating Conditions**

This section lists the functional operating limits for the AC and DC parameters for Stratix V devices. Table 6 lists the steady-state voltage and current values expected from Stratix V devices. Power supply ramps must all be strictly monotonic, without plateaus.

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 1 of 2)

Symbol	Description	Condition	Min <sup>(4)</sup>	Тур	Max <sup>(4)</sup>	Unit
	Core voltage and periphery circuitry power supply (C1, C2, I2, and I3YY speed grades)	_	0.87	0.9	0.93	V
V <sub>CC</sub>	Core voltage and periphery circuitry power supply (C2L, C3, C4, I2L, I3, I3L, and I4 speed grades) (3)	_	0.82	0.85	0.88	V
V <sub>CCPT</sub>	Power supply for programmable power technology	_	1.45	1.50	1.55	V
V <sub>CC_AUX</sub>	Auxiliary supply for the programmable power technology	_	2.375	2.5	2.625	V
V (1)	I/O pre-driver (3.0 V) power supply		2.85	3.0	3.15	V
V <sub>CCPD</sub> <sup>(1)</sup>	I/O pre-driver (2.5 V) power supply		2.375	2.5	2.625	V
	I/O buffers (3.0 V) power supply	_	2.85	3.0	3.15	٧
V <sub>CCIO</sub>	I/O buffers (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply	_	1.71	1.8	1.89	٧
	I/O buffers (1.5 V) power supply	_	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply		1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply		1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	_	1.14	1.2	1.26	V
	Configuration pins (3.0 V) power supply		2.85	3.0	3.15	V
$V_{CCPGM}$	Configuration pins (2.5 V) power supply	_	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	_	1.71	1.8	1.89	V
V <sub>CCA_FPLL</sub>	PLL analog voltage regulator power supply		2.375	2.5	2.625	V
V <sub>CCD_FPLL</sub>	PLL digital voltage regulator power supply		1.45	1.5	1.55	V
V <sub>CCBAT</sub> (2)	Battery back-up power supply (For design security volatile key register)	_	1.2	_	3.0	V
V <sub>I</sub>	DC input voltage	_	-0.5	_	3.6	V
V <sub>0</sub>	Output voltage	_	0	_	V <sub>CCIO</sub>	V
т.	Operating junction temperature	Commercial	0	_	85	°C
T <sub>J</sub>	Operating junction temperature	Industrial	-40	_	100	°C

Page 10 Electrical Characteristics

Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices (1) (Part 2 of 2)

				Calibratio	n Accuracy		
Symbol	Description	Conditions	C1	C2,I2	C3,I3, I3YY	C4,I4	Unit
50-Ω R <sub>S</sub>	Internal series termination with calibration (50- $\Omega$ setting)	V <sub>CCIO</sub> = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%
$34\text{-}\Omega$ and $40\text{-}\Omega$ $R_S$	Internal series termination with calibration (34- $\Omega$ and 40- $\Omega$ setting)	V <sub>CCIO</sub> = 1.5, 1.35, 1.25, 1.2 V	±15	±15	±15	±15	%
$48$ - $\Omega$ , $60$ - $\Omega$ , $80$ - $\Omega$ , and $240$ - $\Omega$ R <sub>S</sub>	Internal series termination with calibration (48- $\Omega$ , 60- $\Omega$ , 80- $\Omega$ , and 240- $\Omega$ setting)	V <sub>CCIO</sub> = 1.2 V	±15	±15	±15	±15	%
50-Ω R <sub>T</sub>	Internal parallel termination with calibration (50-Ω setting)	V <sub>CCIO</sub> = 2.5, 1.8, 1.5, 1.2 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
$\begin{array}{c} 20\text{-}\Omega,30\text{-}\Omega,\\ 40\text{-}\Omega,60\text{-}\Omega,\\ \text{and}\\ 120\text{-}\OmegaR_T \end{array}$	Internal parallel termination with calibration (20- $\Omega$ , 30- $\Omega$ , 40- $\Omega$ , 60- $\Omega$ , and 120- $\Omega$ setting)	V <sub>CCIO</sub> = 1.5, 1.35, 1.25 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
60- $\Omega$ and 120- $\Omega$ R <sub>T</sub>	Internal parallel termination with calibration (60- $\Omega$ and 120- $\Omega$ setting)	V <sub>CCIO</sub> = 1.2	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
$\begin{array}{c} \textbf{25-}\Omega \\ \textbf{R}_{S\_left\_shift} \end{array}$	Internal left shift series termination with calibration (25- $\Omega$ R <sub>S_left_shift</sub> setting)	V <sub>CCIO</sub> = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%

### Note to Table 11:

Table 12 lists the Stratix V OCT without calibration resistance tolerance to PVT changes.

Table 12. OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices (Part 1 of 2)

			Resistance Tolerance					
Symbol	Description	Conditions	<b>C</b> 1	C2,I2	C3, I3, I3YY	C4, I4	Unit	
25-Ω R, 50-Ω R <sub>S</sub>	Internal series termination without calibration (25- $\Omega$ setting)	V <sub>CC10</sub> = 3.0 and 2.5 V	±30	±30	±40	±40	%	
25-Ω R <sub>S</sub>	Internal series termination without calibration (25- $\Omega$ setting)	V <sub>CC10</sub> = 1.8 and 1.5 V	±30	±30	±40	±40	%	
25-Ω R <sub>S</sub>	Internal series termination without calibration (25- $\Omega$ setting)	V <sub>CCIO</sub> = 1.2 V	±35	±35	±50	±50	%	

<sup>(1)</sup> OCT calibration accuracy is valid at the time of calibration only.

Page 14 Electrical Characteristics

Table 18. Single-Ended SSTL, HSTL, and HSUL I/O Reference Voltage Specifications for Stratix V Devices

I/O Standard		V <sub>CCIO</sub> (V)			V <sub>REF</sub> (V)			V <sub>TT</sub> (V)	
I/O Standard	Min	Тур	Max	Min	Тур	Max	Min	Тур	Мах
SSTL-2 Class I, II	2.375	2.5	2.625	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	V <sub>REF</sub> – 0.04	$V_{REF}$	V <sub>REF</sub> + 0.04
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	V <sub>REF</sub> – 0.04	V <sub>REF</sub>	V <sub>REF</sub> + 0.04
SSTL-15 Class I, II	1.425	1.5	1.575	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	0.49 * V <sub>CCIO</sub>	0.5 * VCCIO	0.51 * V <sub>CCIO</sub>
SSTL-135 Class I, II	1.283	1.35	1.418	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>
SSTL-125 Class I, II	1.19	1.25	1.26	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	0.49 * V <sub>CCIO</sub>	0.5 * VCCIO	0.51 * V <sub>CCIO</sub>
SSTL-12 Class I, II	1.14	1.20	1.26	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	0.49 * V <sub>CCIO</sub>	0.5 * VCCIO	0.51 * V <sub>CCIO</sub>
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	_	V <sub>CCIO</sub> /2	_
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	_	V <sub>CCIO</sub> /2	_
HSTL-12 Class I, II	1.14	1.2	1.26	0.47 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.53 * V <sub>CCIO</sub>	_	V <sub>CCIO</sub> /2	_
HSUL-12	1.14	1.2	1.3	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	_	_	_

Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices (Part 1 of 2)

I/O Standard	V <sub>IL(D(</sub>	<sub>c)</sub> (V)	V <sub>IH(D</sub>	<sub>C)</sub> (V)	V <sub>IL(AC)</sub> (V)	V <sub>IH(AC)</sub> (V)	V <sub>OL</sub> (V)	V <sub>OH</sub> (V)	I (mA)	I <sub>oh</sub>
i/U Stanuaru	Min	Max	Min	Max	Max	Min	Max	Min	I <sub>ol</sub> (mA)	(mA)
SSTL-2 Class I	-0.3	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	V <sub>CCIO</sub> + 0.3	V <sub>REF</sub> – 0.31	V <sub>REF</sub> + 0.31	V <sub>TT</sub> – 0.608	V <sub>TT</sub> + 0.608	8.1	-8.1
SSTL-2 Class II	-0.3	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	V <sub>CCIO</sub> + 0.3	V <sub>REF</sub> – 0.31	V <sub>REF</sub> + 0.31	V <sub>TT</sub> – 0.81	V <sub>TT</sub> + 0.81	16.2	-16.2
SSTL-18 Class I	-0.3	V <sub>REF</sub> – 0.125	V <sub>REF</sub> + 0.125	V <sub>CCIO</sub> + 0.3	V <sub>REF</sub> – 0.25	V <sub>REF</sub> + 0.25	V <sub>TT</sub> – 0.603	V <sub>TT</sub> + 0.603	6.7	-6.7
SSTL-18 Class II	-0.3	V <sub>REF</sub> – 0.125	V <sub>REF</sub> + 0.125	V <sub>CCIO</sub> + 0.3	V <sub>REF</sub> – 0.25	V <sub>REF</sub> + 0.25	0.28	V <sub>CCIO</sub> - 0.28	13.4	-13.4
SSTL-15 Class I	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> – 0.175	V <sub>REF</sub> + 0.175	0.2 * V <sub>CCIO</sub>	0.8 * V <sub>CCIO</sub>	8	-8
SSTL-15 Class II	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> – 0.175	V <sub>REF</sub> + 0.175	0.2 * V <sub>CCIO</sub>	0.8 * V <sub>CCIO</sub>	16	-16
SSTL-135 Class I, II	_	V <sub>REF</sub> – 0.09	V <sub>REF</sub> + 0.09	_	V <sub>REF</sub> – 0.16	V <sub>REF</sub> + 0.16	0.2 * V <sub>CCIO</sub>	0.8 * V <sub>CCIO</sub>	_	_
SSTL-125 Class I, II	_	V <sub>REF</sub> – 0.85	V <sub>REF</sub> + 0.85	_	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	0.2 * V <sub>CCIO</sub>	0.8 * V <sub>CCIO</sub>	_	_
SSTL-12 Class I, II	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	0.2 * V <sub>CCIO</sub>	0.8 * V <sub>CCIO</sub>	_	_

Electrical Characteristics Page 15

Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices (Part 2 of 2)

I/O Standard	V <sub>IL(D(</sub>	; <sub>)</sub> (V)	V <sub>IH(D</sub>	<sub>C)</sub> (V)	V <sub>IL(AC)</sub> (V)	V <sub>IH(AC)</sub> (V)	V <sub>OL</sub> (V)	V <sub>OH</sub> (V)	I <sub>ol</sub> (mA)	l <sub>oh</sub>
i/O Stanuaru	Min	Max	Min	Max	Max	Min	Max	Min	I <sub>OI</sub> (IIIA)	(mA)
HSTL-18 Class I	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> - 0.2	V <sub>REF</sub> + 0.2	0.4	V <sub>CCIO</sub> – 0.4	8	-8
HSTL-18 Class II	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> - 0.2	V <sub>REF</sub> + 0.2	0.4	V <sub>CCIO</sub> – 0.4	16	-16
HSTL-15 Class I	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> - 0.2	V <sub>REF</sub> + 0.2	0.4	V <sub>CCIO</sub> – 0.4	8	-8
HSTL-15 Class II	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> - 0.2	V <sub>REF</sub> + 0.2	0.4	V <sub>CCIO</sub> – 0.4	16	-16
HSTL-12 Class I	-0.15	V <sub>REF</sub> – 0.08	V <sub>REF</sub> + 0.08	V <sub>CCIO</sub> + 0.15	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	0.25* V <sub>CCIO</sub>	0.75* V <sub>CCIO</sub>	8	-8
HSTL-12 Class II	-0.15	V <sub>REF</sub> – 0.08	V <sub>REF</sub> + 0.08	V <sub>CCIO</sub> + 0.15	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	0.25* V <sub>CCIO</sub>	0.75* V <sub>CCIO</sub>	16	-16
HSUL-12	_	V <sub>REF</sub> – 0.13	V <sub>REF</sub> + 0.13	_	V <sub>REF</sub> – 0.22	V <sub>REF</sub> + 0.22	0.1* V <sub>CCIO</sub>	0.9* V <sub>CCIO</sub>	_	

Table 20. Differential SSTL I/O Standards for Stratix V Devices

I/O Standard		V <sub>CCIO</sub> (V)		V <sub>SWIN</sub>	<sub>G(DC)</sub> (V)		V <sub>X(AC)</sub> (V)		V <sub>SWING(</sub>	<sub>AC)</sub> (V)
I/O Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.3	V <sub>CCIO</sub> + 0.6	V <sub>CCIO</sub> /2 – 0.2	_	V <sub>CCIO</sub> /2 + 0.2	0.62	V <sub>CCIO</sub> + 0.6
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	V <sub>CCIO</sub> + 0.6	V <sub>CCIO</sub> /2 – 0.175	_	V <sub>CCIO</sub> /2 + 0.175	0.5	V <sub>CCIO</sub> + 0.6
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	(1)	V <sub>CCIO</sub> /2 – 0.15	_	V <sub>CCIO</sub> /2 + 0.15	0.35	_
SSTL-135 Class I, II	1.283	1.35	1.45	0.2	(1)	V <sub>CCIO</sub> /2 – 0.15	V <sub>CCIO</sub> /2	V <sub>CCIO</sub> /2 + 0.15	2(V <sub>IH(AC)</sub> - V <sub>REF</sub> )	2(V <sub>IL(AC)</sub> - V <sub>REF</sub> )
SSTL-125 Class I, II	1.19	1.25	1.31	0.18	(1)	V <sub>CCIO</sub> /2 – 0.15	V <sub>CCIO</sub> /2	V <sub>CCIO</sub> /2 + 0.15	2(V <sub>IH(AC)</sub> - V <sub>REF</sub> )	_
SSTL-12 Class I, II	1.14	1.2	1.26	0.18	_	V <sub>REF</sub> -0.15	V <sub>CCIO</sub> /2	V <sub>REF</sub> + 0.15	-0.30	0.30

### Note to Table 20:

Table 21. Differential HSTL and HSUL I/O Standards for Stratix V Devices (Part 1 of 2)

I/O				V <sub>DIF(</sub>	<sub>DC)</sub> (V)	V <sub>X(AC)</sub> (V)				V <sub>CM(DC)</sub> (V	V <sub>DIF(AC)</sub> (V)		
Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	_	0.78	_	1.12	0.78	_	1.12	0.4	_
HSTL-15 Class I, II	1.425	1.5	1.575	0.2		0.68	_	0.9	0.68		0.9	0.4	_

<sup>(1)</sup> The maximum value for  $V_{SWING(DC)}$  is not defined. However, each single-ended signal needs to be within the respective single-ended limits  $(V_{IH(DC)})$  and  $V_{IL(DC)})$ .

Page 24 Switching Characteristics

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 7 of 7)

Symbol/ Description	Conditions	Trai	Sceiver Speed Transceiver Speed Transceiver Speed Grade 1 Grade 2 Grade 3			Transceiver Speed Grade 1								
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max				
t <sub>pll_lock</sub> (16)	_		_	10	_	_	10	_	_	10	μs			

#### Notes to Table 23:

- (1) Speed grades shown in Table 23 refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Stratix V Device Overview*.
- (2) The reference clock common mode voltage is equal to the  $V_{CCR\_GXB}$  power supply level.
- (3) This supply must be connected to 1.0 V if the transceiver is configured at a data rate > 6.5 Gbps, and to 1.05 V if configured at a data rate > 10.3 Gbps when DFE is used. For data rates up to 6.5 Gbps, you can connect this supply to 0.85 V.
- (4) This supply follows VCCR\_GXB.
- (5) The device cannot tolerate prolonged operation at this absolute maximum.
- (6) The differential eye opening specification at the receiver input pins assumes that **Receiver Equalization** is disabled. If you enable **Receiver Equalization**, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (7) The Quartus II software automatically selects the appropriate slew rate depending on the configured data rate or functional mode.
- (8) The input reference clock frequency options depend on the data rate and the device speed grade.
- (9) The line data rate may be limited by PCS-FPGA interface speed grade.
- (10) Refer to Figure 1 for the GX channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (11) t<sub>LTR</sub> is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (12) t<sub>I TD</sub> is time required for the receiver CDR to start recovering valid data after the rx\_is\_lockedtodata signal goes high.
- (13) t<sub>LTD\_manual</sub> is the time required for the receiver CDR to start recovering valid data after the rx\_is\_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (14) t<sub>LTR\_LTD\_manual</sub> is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx\_is\_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (15)  $t_{pll\ powerdown}$  is the PLL powerdown minimum pulse width.
- (16) t<sub>nll lock</sub> is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (17) To calculate the REFCLK rms phase jitter requirement for PCle at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (18) The maximum peak to peak differential input voltage V<sub>ID</sub> after device configuration is equal to 4 × (absolute V<sub>MAX</sub> for receiver pin V<sub>ICM</sub>).
- (19) For ES devices,  $R_{REF}$  is 2000  $\Omega$  ±1%.
- (20) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20\*log(f/622).
- (21) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (22) Refer to Figure 2.
- (23) For oversampling designs to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (24) I3YY devices can achieve data rates up to 10.3125 Gbps.
- (25) When you use fPLL as a TXPLL of the transceiver.
- (26) REFCLK performance requires to meet transmitter REFCLK phase noise specification.
- (27) Minimum eye opening of 85 mV is only for the unstressed input eye condition.

Switching Characteristics Page 27

Table 26 shows the approximate maximum data rate using the 10G PCS.

Table 26. Stratix V 10G PCS Approximate Maximum Data Rate (1)

Mode (2)	Transceiver	PMA Width	64	40	40	40	32	32		
Speed Grade		PCS Width	64	66/67	50	40	64/66/67	32		
	1	C1, C2, C2L, I2, I2L core speed grade	14.1	14.1	10.69	14.1	13.6	13.6		
	2	C1, C2, C2L, I2, I2L core speed grade	12.5	12.5	10.69	12.5	12.5	12.5		
		C3, I3, I3L core speed grade	12.5	12.5	10.69	12.5	10.88	10.88		
FIFO or Register		C1, C2, C2L, I2, I2L core speed grade								
	3	C3, I3, I3L core speed grade	8.5 Gbps							
	3	C4, I4 core speed grade								
		I3YY core speed grade	10 3125 Ghne							

### Notes to Table 26:

<sup>(1)</sup> The maximum data rate is in Gbps.

<sup>(2)</sup> The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

Switching Characteristics Page 29

Figure 2 shows the differential transmitter output waveform.

Figure 2. Differential Transmitter Output Waveform

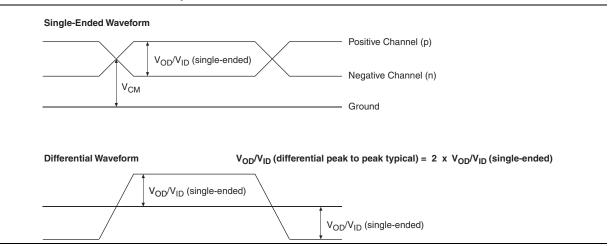


Figure 3 shows the Stratix V AC gain curves for GX channels.

Figure 3. AC Gain Curves for GX Channels (full bandwidth)



Stratix V GT devices contain both GX and GT channels. All transceiver specifications for the GX channels not listed in Table 28 are the same as those listed in Table 23.

Table 28 lists the Stratix V GT transceiver specifications.

Page 30 Switching Characteristics

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 1 of 5)  $^{(1)}$ 

Symbol/	Conditions	S	Transceive Speed Grade			Transceive peed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	<b>5</b>
Reference Clock	l		<u>I</u>	ul.			<u>I</u>	<u>I</u>
Supported I/O Standards	Dedicated reference clock pin	1.2-V PCN	1L, 1.4-V PC	ML, 1.5-V P(	CML, 2.5-V I and HCSL	PCML, Diffe	rential LVPE	ECL, LVDS
otandardo	RX reference clock pin		1.4-V PCML	., 1.5-V PCN	IL, 2.5-V PC	ML, LVPEC	L, and LVDS	3
Input Reference Clock Frequency (CMU PLL) <sup>(6)</sup>	_	40	_	710	40	_	710	MHz
Input Reference Clock Frequency (ATX PLL) (6)	_	100	_	710	100	_	710	MHz
Rise time	e time 20% to 80%		_	400	_	_	400	
Fall time	80% to 20%	_	_	400	_	<u> </u>	400	ps
Duty cycle	_	45	_	55	45	_	55	%
Spread-spectrum modulating clock frequency	PCI Express (PCIe)	30	_	33	30	_	33	kHz
Spread-spectrum downspread	PCle		0 to -0.5	_	_	0 to -0.5	_	%
On-chip termination resistors (19)	_	_	100	_	_	100	_	Ω
Absolute V <sub>MAX</sub> (3)	Dedicated reference clock pin	_	_	1.6	_	_	1.6	V
	RX reference clock pin	_	_	1.2	_	_	1.2	
Absolute V <sub>MIN</sub>	_	-0.4	_	_	-0.4		_	V
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	mV
V <sub>ICM</sub> (AC coupled)	Dedicated reference clock pin		1050/1000	2)	1	050/1000	2)	mV
	RX reference clock pin	1	.0/0.9/0.85	(22)	1.	0/0.9/0.85	(22)	V
V <sub>ICM</sub> (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	mV

Switching Characteristics Page 37

Figure 6 shows the Stratix V DC gain curves for GT channels.

## Figure 6. DC Gain Curves for GT Channels

## **Transceiver Characterization**

This section summarizes the Stratix V transceiver characterization results for compliance with the following protocols:

- Interlaken
- 40G (XLAUI)/100G (CAUI)
- 10GBase-KR
- QSGMII
- XAUI
- SFI
- Gigabit Ethernet (Gbe / GIGE)
- SPAUI
- Serial Rapid IO (SRIO)
- CPRI
- OBSAI
- Hyper Transport (HT)
- SATA
- SAS
- CEI

Page 38 Switching Characteristics

- XFI
- ASI
- HiGig/HiGig+
- HiGig2/HiGig2+
- Serial Data Converter (SDC)
- GPON
- SDI
- SONET
- Fibre Channel (FC)
- PCIe
- QPI
- SFF-8431

Download the Stratix V Characterization Report Tool to view the characterization report summary for these protocols.

## **Core Performance Specifications**

This section describes the clock tree, phase-locked loop (PLL), digital signal processing (DSP), memory blocks, configuration, and JTAG specifications.

## **Clock Tree Specifications**

Table 30 lists the clock tree specifications for Stratix V devices.

Table 30. Clock Tree Performance for Stratix V Devices (1)

	Performance						
Symbol	C1, C2, C2L, I2, and I2L	C3, I3, I3L, and I3YY	C4, I4	Unit			
Global and Regional Clock	717	650	580	MHz			
Periphery Clock	550	500	500	MHz			

### Note to Table 30:

(1) The Stratix V ES devices are limited to 600 MHz core clock tree performance.

Page 42 Switching Characteristics

Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 2 of 2)

		Peformance							
Mode	C1	C2, C2L	12, 12L	C3	13, 13L, 13YY	C4	14	Unit	
		Modes us	ing Three	DSPs	•				
One complex 18 x 25	425	425	415	340	340	275	265	MHz	
Modes using Four DSPs									
One complex 27 x 27	465	465	465	380	380	300	290	MHz	

# **Memory Block Specifications**

Table 33 lists the Stratix V memory block specifications.

Table 33. Memory Block Performance Specifications for Stratix V Devices (1), (2) (Part 1 of 2)

		Resources Used		Performance							
Memory	Mode	ALUTS	Memory	C1	C2, C2L	C3	C4	12, I2L	13, 13L, 13YY	14	Unit
	Single port, all supported widths	0	1	450	450	400	315	450	400	315	MHz
MLAB	Simple dual-port, x32/x64 depth	0	1	450	450	400	315	450	400	315	MHz
IVILAD	Simple dual-port, x16 depth (3)	0	1	675	675	533	400	675	533	400	MHz
	ROM, all supported widths	0	1	600	600	500	450	600	500	450	MHz

Configuration Specification Page 53

Table 46.	JTAG Timino	Parameters a	nd Values	for Stratix V Devices
-----------	-------------	--------------	-----------	-----------------------

Symbol	Description	Min	Max	Unit
t <sub>JPH</sub>	JTAG port hold time	5	_	ns
t <sub>JPCO</sub>	JTAG port clock to output	_	11 <sup>(1)</sup>	ns
t <sub>JPZX</sub>	JTAG port high impedance to valid output	_	14 <sup>(1)</sup>	ns
t <sub>JPXZ</sub>	JTAG port valid output to high impedance	_	14 <sup>(1)</sup>	ns

### Notes to Table 46:

- (1) A 1 ns adder is required for each  $V_{CCIO}$  voltage step down from 3.0 V. For example,  $t_{JPCO}$  = 12 ns if  $V_{CCIO}$  of the TDO I/O bank = 2.5 V, or 13 ns if it equals 1.8 V.
- (2) The minimum TCK clock period is 167 ns if VCCBAT is within the range 1.2V-1.5V when you perform the volatile key programming.

# **Raw Binary File Size**

For the POR delay specification, refer to the "POR Delay Specification" section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices".

Table 47 lists the uncompressed raw binary file (.rbf) sizes for Stratix V devices.

Table 47. Uncompressed .rbf Sizes for Stratix V Devices

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) (4), (5)	
	ECCVAO	H35, F40, F35 <sup>(2)</sup>	213,798,880	562,392	
	5SGXA3	H29, F35 <sup>(3)</sup>	137,598,880	564,504	
	5SGXA4	_	213,798,880	563,672	
	5SGXA5	_	269,979,008	562,392	
	5SGXA7	_	269,979,008	562,392	
Stratix V GX	5SGXA9	_	342,742,976	700,888	
	5SGXAB	_	342,742,976	700,888	
	5SGXB5	_	270,528,640	584,344	
	5SGXB6	_	270,528,640	584,344	
	5SGXB9	_	342,742,976	700,888	
	5SGXBB	_	342,742,976	700,888	
Chrotin V CT	5SGTC5	_	269,979,008	562,392	
Stratix V GT	5SGTC7	_	269,979,008	562,392	
	5SGSD3	_	137,598,880	564,504	
	FCCCD4	F1517	213,798,880	563,672	
Ctrativ V CC	5SGSD4	_	137,598,880	564,504	
Stratix V GS	5SGSD5	_	213,798,880	563,672	
	5SGSD6	_	293,441,888	565,528	
	5SGSD8	_	293,441,888	565,528	

Page 54 Configuration Specification

Table 47. Uncompressed .rbf Sizes for Stratix V Devices

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) (4), (5)	
Stratix V E (1)	5SEE9	_	342,742,976	700,888	
Stratix V L 17	5SEEB	_	342,742,976	700,888	

#### Notes to Table 47:

- (1) Stratix V E devices do not have PCI Express® (PCIe®) hard IP. Stratix V E devices do not support the CvP configuration scheme.
- (2) 36-transceiver devices.
- (3) 24-transceiver devices.
- (4) File size for the periphery image.
- (5) The IOCSR .rbf size is specifically for the CvP feature.

Use the data in Table 47 to estimate the file size before design compilation. Different configuration file formats, such as a hexadecimal (.hex) or tabular text file (.ttf) format, have different file sizes. For the different types of configuration file and file sizes, refer to the Quartus II software. However, for a specific version of the Quartus II software, any design targeted for the same device has the same uncompressed configuration file size. If you are using compression, the file size can vary after each compilation because the compression ratio depends on your design.

For more information about setting device configuration options, refer to *Configuration, Design Security, and Remote System Upgrades in Stratix V Devices.* For creating configuration files, refer to the *Quartus II Help*.

Table 48 lists the minimum configuration time estimates for Stratix V devices.

Table 48. Minimum Configuration Time Estimation for Stratix V Devices

	Banker		Active Serial (1)	)	Fast Passive Parallel <sup>(2)</sup>			
Variant	Member Code	Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)	
	۸٥	4	100	0.534	32	100	0.067	
	A3	4	100	0.344	32	100	0.043	
	A4	4	100	0.534	32	100	0.067	
	A5	4	100	0.675	32	100	0.084	
	A7	4	100	0.675	32	100	0.084	
GX	A9	4	100	0.857	32	100	0.107	
	AB	4	100	0.857	32	100	0.107	
	B5	4	100	0.676	32	100	0.085	
	B6	4	100	0.676	32	100	0.085	
	В9	4	100	0.857	32	100	0.107	
	BB	4	100	0.857	32	100	0.107	
GT	C5	4	100	0.675	32	100	0.084	
G1	C7	4	100	0.675	32	100	0.084	

Configuration Specification Page 55

Table 48. Minimum Configuration Time Estimation for Stratix V Devices

	Member Code		Active Serial (1)	1	Fast Passive Parallel (2)			
Variant		Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)	
	D3	4	100	0.344	32	100	0.043	
	D4	4	100	0.534	32	100	0.067	
GS		4	100	0.344	32	100	0.043	
us	D5	4	100	0.534	32	100	0.067	
	D6	4	100	0.741	32	100	0.093	
	D8	4	100	0.741	32	100	0.093	
E	E9	4	100	0.857	32	100	0.107	
Е	EB	4	100	0.857	32	100	0.107	

### Notes to Table 48:

# **Fast Passive Parallel Configuration Timing**

This section describes the fast passive parallel (FPP) configuration timing parameters for Stratix V devices.

## DCLK-to-DATA[] Ratio for FPP Configuration

FPP configuration requires a different DCLK-to-DATA[] ratio when you enable the design security, decompression, or both features. Table 49 lists the DCLK-to-DATA[] ratio for each combination.

Table 49. DCLK-to-DATA[] Ratio (1) (Part 1 of 2)

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×8	Disabled	Enabled	1
IFF X0	Enabled	Disabled	2
	Enabled	Enabled	2
	Disabled	Disabled	1
FPP ×16	Disabled	Enabled	2
IFF XIO	Enabled	Disabled	4
	Enabled	Enabled	4

<sup>(1)</sup> DCLK frequency of 100 MHz using external CLKUSR.

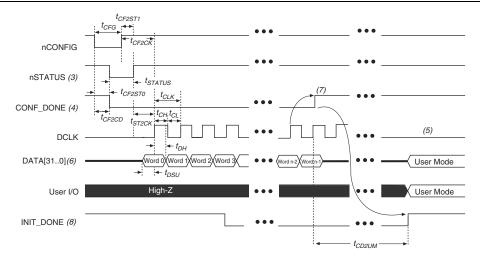
<sup>(2)</sup> Max FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

Configuration Specification Page 57

## FPP Configuration Timing when DCLK-to-DATA [] = 1

Figure 12 shows the timing waveform for FPP configuration when using a MAX II or MAX V device as an external host. This waveform shows timing when the DCLK-to-DATA[] ratio is 1.

Figure 12. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is 1 (1), (2)



### Notes to Figure 12:

- (1) Use this timing waveform when the DCLK-to-DATA[] ratio is 1.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic-high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (4) After power-up, before and during configuration, CONF DONE is low.
- (5) Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
- (6) For FPP ×16, use DATA [15..0]. For FPP ×8, use DATA [7..0]. DATA [31..0] are available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings.
- (7) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF\_DONE is released high when the Stratix V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (8) After the option bit to enable the <code>INIT\_DONE</code> pin is configured into the device, the <code>INIT\_DONE</code> goes low.

Page 58 Configuration Specification

Table 50 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA[] ratio is 1.

Table 50. FPP Timing Parameters for Stratix V Devices (1)

Symbol	Parameter	Minimum	Maximum	Units
t <sub>CF2CD</sub>	nCONFIG low to CONF_DONE low	_	600	ns
t <sub>CF2ST0</sub>	nconfig low to nstatus low	_	600	ns
t <sub>CFG</sub>	nCONFIG low pulse width	2	_	μS
t <sub>STATUS</sub>	nstatus low pulse width	268	1,506 <sup>(2)</sup>	μS
t <sub>CF2ST1</sub>	nCONFIG high to nSTATUS high	_	1,506 <sup>(3)</sup>	μS
t <sub>CF2CK</sub> (6)	nCONFIG high to first rising edge on DCLK	1,506	_	μS
t <sub>ST2CK</sub> (6)	nSTATUS high to first rising edge of DCLK	2	_	μS
t <sub>DSU</sub>	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t <sub>DH</sub>	DATA[] hold time after rising edge on DCLK	0	_	ns
t <sub>CH</sub>	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t <sub>CL</sub>	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t <sub>CLK</sub>	DCLK period	1/f <sub>MAX</sub>	_	S
f	DCLK frequency (FPP ×8/×16)	_	125	MHz
f <sub>MAX</sub>	DCLK frequency (FPP ×32)	_	100	MHz
t <sub>CD2UM</sub>	CONF_DONE high to user mode (4)	175	437	μS
+	GOVER DOVER high to GUVERN anabled	4 × maximum		
t <sub>CD2CU</sub>	CONF_DONE high to CLKUSR enabled	DCLK period	_	
t <sub>CD2UMC</sub>	CONF_DONE high to user mode with CLKUSR option on	t <sub>CD2CU</sub> + (8576 × CLKUSR period) <sup>(5)</sup>	_	_

#### Notes to Table 50:

- (1) Use these timing parameters when the decompression and design security features are disabled.
- (2) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (3) This value is applicable if you do not delay configuration by externally holding the nstatus low.
- (4) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.
- (5) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (6) If nSTATUS is monitored, follow the t<sub>ST2CK</sub> specification. If nSTATUS is not monitored, follow the t<sub>CF2CK</sub> specification.

## FPP Configuration Timing when DCLK-to-DATA [] > 1

Figure 13 shows the timing waveform for FPP configuration when using a MAX II device, MAX V device, or microprocessor as an external host. This waveform shows timing when the DCLK-to-DATA [] ratio is more than 1.

Page 64 I/O Timing

# **Remote System Upgrades**

Table 56 lists the timing parameter specifications for the remote system upgrade circuitry.

**Table 56. Remote System Upgrade Circuitry Timing Specifications** 

Parameter	Minimum	Maximum	Unit
t <sub>RU_nCONFIG</sub> (1)	250	_	ns
t <sub>RU_nRSTIMER</sub> (2)	250	_	ns

#### Notes to Table 56:

- (1) This is equivalent to strobing the reconfiguration input of the ALTREMOTE\_UPDATE megafunction high for the minimum timing specification. For more information, refer to the Remote System Upgrade State Machine section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (2) This is equivalent to strobing the reset\_timer input of the ALTREMOTE\_UPDATE megafunction high for the minimum timing specification. For more information, refer to the User Watchdog Timer section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

## **User Watchdog Internal Circuitry Timing Specification**

Table 57 lists the operating range of the 12.5-MHz internal oscillator.

**Table 57. 12.5-MHz Internal Oscillator Specifications** 

Minimum	Typical	Maximum	Units		
5.3	7.9	12.5	MHz		

# I/O Timing

Altera offers two ways to determine I/O timing—the Excel-based I/O Timing and the Quartus II Timing Analyzer.

Excel-based I/O timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis. The Quartus II Timing Analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after you complete place-and-route.

You can download the Excel-based I/O Timing spreadsheet from the Stratix V Devices Documentation web page.

# **Programmable IOE Delay**

Table 58 lists the Stratix V IOE programmable delay settings.

Table 58. IOE Programmable Delay for Stratix V Devices (Part 1 of 2)

Poromotor Avoilable		Min	Fast	Model				Slow M	lodel			
Parameter (1)	Available Settings	Offset (2)	Industrial	Commercial	C1	C2	C3	C4	12	13, 13YY	14	Unit
D1	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D2	32	0	0.230	0.244	0.415	0.415	0.459	0.503	0.417	0.456	0.500	ns

Glossary Page 65

Table 58. IOE Programmable Delay for Stratix V Devices (Part 2 of 2)

Parameter Availal	Available	Min Fast Model			Slow Model							
(1)	Settings	Offset (2)	Industrial	Commercial	C1	C2	C3	C4	12	13, 13YY	14	Unit
D3	8	0	1.587	1.699	2.793	2.793	2.992	3.192	2.811	3.047	3.257	ns
D4	64	0	0.464	0.492	0.838	0.838	0.924	1.011	0.843	0.920	1.006	ns
D5	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D6	32	0	0.229	0.244	0.415	0.415	0.458	0.503	0.418	0.456	0.499	ns

### Notes to Table 58:

- (1) You can set this value in the Quartus II software by selecting D1, D2, D3, D5, and D6 in the Assignment Name column of Assignment Editor.
- (2) Minimum offset does not include the intrinsic delay.

## **Programmable Output Buffer Delay**

Table 59 lists the delay chain settings that control the rising and falling edge delays of the output buffer. The default delay is 0 ps.

Table 59. Programmable Output Buffer Delay for Stratix V Devices (1)

Symbol	Parameter	Typical	Unit	
		0 (default)	ps	
D	Rising and/or falling edge delay	25	ps	
D <sub>OUTBUF</sub>		50	ps	
		75	ps	

### Note to Table 59:

# **Glossary**

Table 60 lists the glossary for this chapter.

Table 60. Glossary (Part 1 of 4)

Letter	Subject	Definitions
Α		
В	_	_
С		
D	D — — —	
E	_	
	f <sub>HSCLK</sub> Left and right PLL input clock frequency.	
F	f <sub>HSDR</sub>	High-speed I/O block—Maximum and minimum <b>LVDS</b> data transfer rate (f <sub>HSDR</sub> = 1/TUI), non-DPA.
	f <sub>HSDRDPA</sub>	High-speed I/O block—Maximum and minimum <b>LVDS</b> data transfer rate (f <sub>HSDRDPA</sub> = 1/TUI), DPA.

<sup>(1)</sup> You can set the programmable output buffer delay in the Quartus II software by setting the Output Buffer Delay Control assignment to either positive, negative, or both edges, with the specific values stated here (in ps) for the Output Buffer Delay assignment.

Page 68 Glossary

## Table 60. Glossary (Part 4 of 4)

Letter	Subject	Definitions
	V <sub>CM(DC)</sub>	DC common mode input voltage.
	V <sub>ICM</sub>	Input common mode voltage—The common mode of the differential signal at the receiver.
	V <sub>ID</sub>	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
	V <sub>DIF(AC)</sub>	AC differential input voltage—Minimum AC input differential voltage required for switching.
	V <sub>DIF(DC)</sub>	DC differential input voltage— Minimum DC input differential voltage required for switching.
	V <sub>IH</sub>	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.
	V <sub>IH(AC)</sub>	High-level AC input voltage
	V <sub>IH(DC)</sub>	High-level DC input voltage
V	<b>V</b> <sub>IL</sub>	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.
	V <sub>IL(AC)</sub>	Low-level AC input voltage
	V <sub>IL(DC)</sub>	Low-level DC input voltage
	V <sub>OCM</sub>	Output common mode voltage—The common mode of the differential signal at the transmitter.
	<b>V</b> <sub>OD</sub>	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
	V <sub>SWING</sub>	Differential input voltage
	V <sub>X</sub>	Input differential cross point voltage
	<b>V</b> <sub>OX</sub>	Output differential cross point voltage
W	W	High-speed I/O block—clock boost factor
Χ		
Υ		_
Z		